



HAD825SP

NPN EPITAXIAL PLANAR TRANSISTOR

Features

Darlington Transistor

Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCB0 Collector to Base Voltage 80 V
 VCES Collector to Emitter Voltage 55 V
 VEBO Emitter to Base Voltage 12 V
 IC Collector Current 600 mA

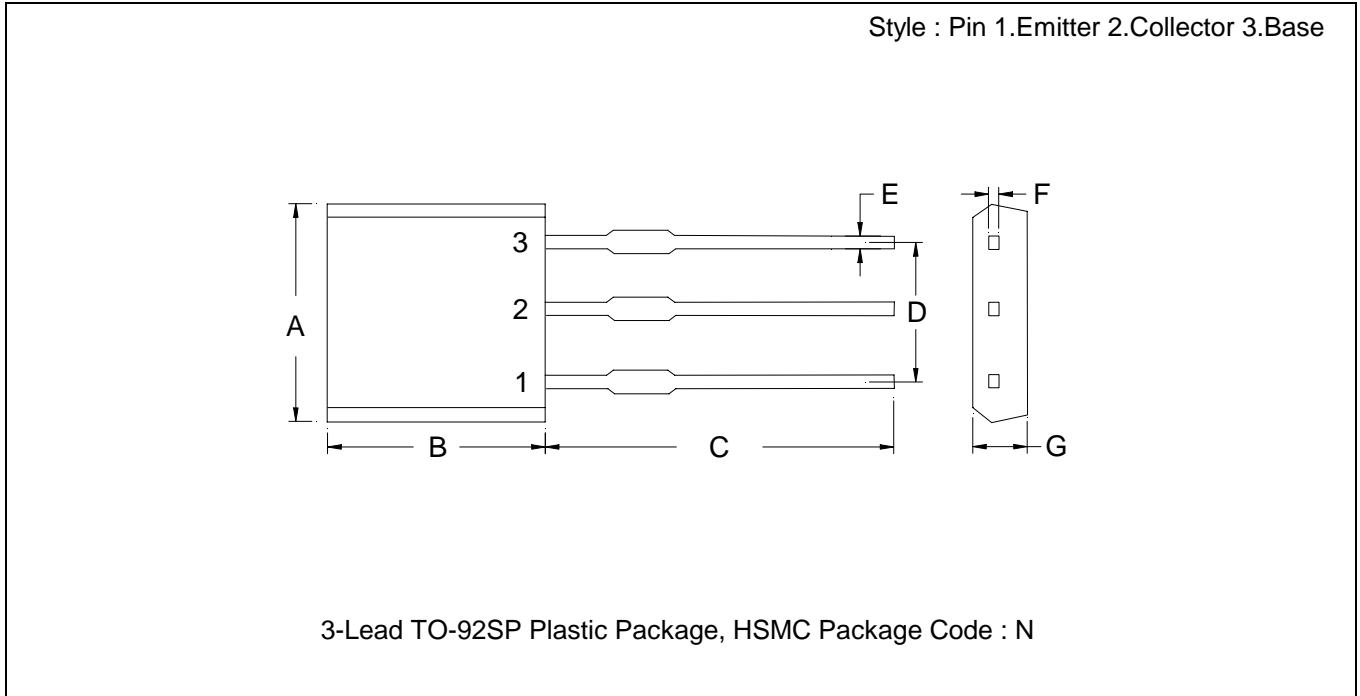
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	80	-	-	V	IC=100uA, IE=0
BVCES	55	-	-	V	IC=100uA, IB=0
BVEBO	12	-	-	V	IE=10uA, IC=0
ICBO	-	-	100	nA	VCB=60V, IE=0
IEBO	-	-	100	nA	VEB=10V, IC=0
ICES	-	-	500	nA	VCE=50V, IB=0
*VCE(sat)1	-	-	1.2	V	IC=10mA, IB=0.01mA
*VCE(sat)2	-	-	1.5	V	IC=100mA, IB=0.1mA
*VBE(on)	-	-	1.5	V	IC=100mA, VCE=5V
*hFE1	10K	-	-		IC=10mA, VCE=5V
*hFE2	10K	-	100K		IC=100mA, VCE=5V
fT	125	-	-	MHz	VCE=5V, IC=10mA, f =100MHz
Cob	-	-	8	pF	VCB=10V, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



TO-92SP Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1450	0.1650	3.70	4.20	E	0.0160	0.0240	0.41	0.61
B	0.1063	0.1300	2.70	3.30	F	-	*0.0150	-	*0.38
C	0.5000	-	12.7	-	G	0.0800	0.1050	2.03	2.67
D	-	*0.1000	-	*2.54					

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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